Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Previously Presented) A dielectric paste comprising ethyl cellulose having an apparent weight average molecular weight of 110,000 to 190,000 as a binder and at least one kind of solvent selected from the group consisting of isobornyl acetate, α-terpinyl acetate, I-dihydrocarvyl acetate, I-menthyl acetate, I-menthone, I-perillyl acetate and I-carvyl acetate.

2. (Original) A dielectric paste adapted for forming a spacer layer in accordance with Claim 1, wherein ethyl cellulose having an apparent weight average molecular weight of 115,000 to 180,000 is contained as a binder.

3. (Currently Amended) A method for fabricating a multi-layered unit for a multi-layered ceramic electronic component comprising a step of printing a dielectric paste including ethyl cellulose having an apparent weight average molecular weight of 110,000 to 190,000 as a binder and at least one kind of solvent selected from the group consisting of isobornyl acetate, α-terpinyl acetate, I-dihydrocarvyl acetate, I-menthyl acetate, I-menthone, I-perillyl acetate and I-carvyl acetate on a ceramic green sheet containing a butyral system resin as a binder in a predetermined pattern, thereby forming a spacer ~~layer~~ layer, the degree of polymerization of the butyral system resin is equal to or larger than 1000, the degree of butyralization of the butyral system resin being equal to or larger than 64 mol % and equal to or smaller than 78 mol %.

4. (Original) A method for fabricating a multi-layered unit for a multi-layered ceramic electronic component in accordance with Claim 3, wherein the dielectric paste

contains ethyl cellulose having an apparent weight average molecular weight of 115,000 to

180,000 is contained as a binder.

        5.   (Canceled)

        6.   (Canceled)